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#### **Description**

The 74LVCE1G08 is a single 2-input positive AND gate with a standard totem pole output. The device is designed for operation with a power supply range of 1.4V to 5.5V. The inputs are tolerant to 5.5V allowing this device to be used in a mixed voltage environment. The device is fully specified for partial power down applications using  $I_{\text{OFF}}$ . The  $I_{\text{OFF}}$  circuitry disables the output preventing damaging current backflow when the device is powered down.

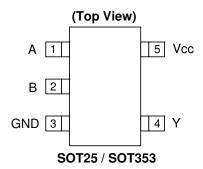
The gate performs the positive Boolean function:

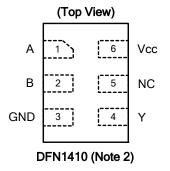
$$Y=A\bullet B \ \text{or} \ Y=\overline{\overline{A}+\overline{B}}$$

#### **Features**

- Extended Supply Voltage Range from 1.4 to 5.5V
- Switching speed characterized for operation at 1.5V
- Offers 30% speed improvement over LVC at 1.8V.
- ± 24mA Output Drive at 3.3V
- CMOS low power consumption
- IOFF Supports Partial-Power-Down Mode Operation
- Inputs accept up to 5.5V
- ESD Protection Tested per JESD 22
   Exceeds 200-V Machine Model (A115-A)
   Exceeds 2000-V Human Body Model (A114-A)
- Latch-Up Exceeds 100mA per JESD 78, Class II
- · Range of Package Options
- · Direct Interface with TTL Levels
- SOT25, SOT353, and DFN1410:
   Available in "Green" Molding Compound (no Br, Sb)
- Lead Free Finish/ RoHS Compliant (Note 1)

### **Pin Assignments**





### **Applications**

- · Voltage Level Shifting
- · General Purpose Logic
- · Wide array of products such as.
  - PCs, networking, notebooks, netbooks, PDAs
  - o Computer peripherals, hard drives, CD/DVD ROM
  - o TV, DVD, DVR, set top box
  - o Cell Phones, Personal Navigation / GPS
  - o MP3 players ,Cameras, Video Recorders

Notes: 1. EU Directive 2002/95/EC (RoHS). All applicable RoHS exemptions applied. Please visit our website at http://www.diodes.com/products/lead\_free.html.

2. Pin 2 and pin 5 of the DFN1410 package are internally connected.



# **Pin Descriptions**

Pin Name	Description			
Α	Data Input			
В	Data Input			
GND	Ground			
Y	Data Output			
Vcc	Supply Voltage			

# **Logic Diagram**



# **Function Table**

Inpi	Output	
Α	В	Υ
Н	Н	Н
L	Χ	L
Χ	L	L



# **Absolute Maximum Ratings (Note 3)**

Symbol	Description	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	KV
ESD MM	Machine Model ESD Protection	200	V
V <sub>CC</sub>	Supply Voltage Range	-0.5 to 6.5	V
Vı	Input Voltage Range	-0.5 to 6.5	V
Vo	Voltage applied to output in high impedance or I <sub>OFF</sub> state	-0.5 to 6.5	V
V <sub>o</sub>	Voltage applied to output in high or low state	-0.3 to V <sub>CC</sub> +0.5	V
I <sub>IK</sub>	Input Clamp Current V <sub>I</sub> <0	-50	mA
I <sub>OK</sub>	Output Clamp Current	-50	mA
Io	Continuous output current	±50	mA
	Continuous current through Vdd or GND	±100	mA
T <sub>J</sub>	Operating Junction Temperature	-40 to 150	°C
T <sub>STG</sub>	Storage Temperature	-65 to 150	°C

Note: 3. Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.



# **Recommended Operating Conditions (Note 4)**

Symbol		Parameter	Min	Max	Unit
\/	Operating Voltage	Operating	1.4	5.5	V
V <sub>CC</sub>	Operating Voltage	Data retention only	1.2		V
		V <sub>CC</sub> = 1.4 V to 1.95 V	0.65 X V <sub>CC</sub>		
V <sub>IH</sub>	High lovel Input Veltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7		V
V <sub>IH</sub>	High-level Input Voltage	$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$	2		V
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	0.7 X V <sub>CC</sub>		I
		$V_{CC} = 1.4 \text{ V to } 1.95 \text{ V}$		0.35 X V <sub>CC</sub>	,
V <sub>IL</sub>	V <sub>IL</sub> Low-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		0.7	V
V IL	Low-level input voltage	V <sub>CC</sub> = 3 V to 3.6 V		0.8	v
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		0.3 X V <sub>CC</sub>	I
V <sub>I</sub>	Input Voltage		0	5.5	V
Vo	Output Voltage		0	V <sub>CC</sub>	V
	High-level output current	Vcc=1.4 V		-3	ı
		V <sub>CC</sub> = 1.65 V		-4	
I <sub>OH</sub>		$V_{CC} = 2.3 \text{ V}$		-8	mA
IOH	I light-level output current	$V_{CC} = 3 \text{ V}$		-16	1117
				-24	
		$V_{CC} = 4.5 \text{ V}$		-32	I
		Vcc=1.4 V		3	ı
		$V_{CC} = 1.65 \text{ V}$		4	ı
I <sub>OL</sub>	Low-level output current	$V_{CC} = 2.3 \text{ V}$		8	mA
IOL	Low-level output current	$V_{CC} = 3 V$		16	ı
		V <sub>CC</sub> = 3 V		24	<u> </u>
		$V_{CC} = 4.5 \text{ V}$		32	I
	1	$V_{CC} = 1.4 \text{ to } 3V$		20	· · · · · · · · · · · · · · · · · · ·
Δt/ΔV	Input transition rise or fall rate	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$		10	ns/V
	Tale	$V_{CC} = 5 \text{ V} \pm 0.5 \text{ V}$		5	1
T <sub>A</sub>	Operating free-air temperature		-40	85	ōC

Note: 4. Unused inputs should be held at Vcc or Ground.



# Electrical Characteristics (All typical values are at Vcc = 3.3V, T<sub>A</sub> = 25°C)

Over recommended free-air temperature range (unless otherwise noted)

Symbol	Parameter	<b>Test Conditions</b>	Vcc	Min	Тур.	Max	Unit
		$I_{OH} = -100 \mu A$	1.4 V to 5.5V	V <sub>CC</sub> - 0.1			
		$I_{OH} = -3mA$	1.4 V	1.05			1
		$I_{OH} = -4mA$	1.65 V	1.2			1
$V_{OH}$	High Level Output Voltage	$I_{OH} = -8mA$	2.3V	1.9			V
	Voltage	I <sub>OH</sub> = -16mA		2.4			1
		$I_{OH} = -24mA$	3 V	2.3			]
		I <sub>OH</sub> = -32mA	4.5 V	3.8			
		$I_{OL} = 100 \mu A$	1.4 V to 5.5V			0.1	
		$I_{OL} = 3mA$	1.4 V			.4	
		$I_{OL} = 4mA$	1.65 V			0.45	
V <sub>OL</sub>	High-level Input Voltage	I <sub>OL</sub> = 8mA	2.3V			0.3	V
		I <sub>OL</sub> = 16mA	3 V			0.4	
		$I_{OL} = 24mA$	3 V			0.55	
		$I_{OL} = 32mA$	4.5			0.55	]
I <sub>I</sub>	Input Current	$V_I = 5.5 \text{ V or GND}$	0 to 5.5 V			± 5	μA
I <sub>OFF</sub>	Power Down Leakage Current	$V_1$ or $V_0 = 5.5V$	0			± 10	μA
I <sub>CC</sub>	Supply Current	$V_1 = 5.5V$ of GND $I_0=0$	1.4 V to 5.5V			10	μA
$\Delta I_{CC}$	Additional Supply Current	One input at V <sub>CC</sub> – 0.6 V Other inputs at V <sub>CC</sub> or GND	3 V to 5.5V			500	μA
Ci	Input Capacitance	$V_i = V_{CC} - \text{ or GND}$	3.3		3.5		pF
		SOT25	(Note 5)		204		
$\theta_{JA}$	Thermal Resistance Junction-to-Ambient	SOT353	(Note 5)		371		°C/W
	Junction-to-Ambient	DFN1410	(Note 5)		430		1
		SOT25	(Note 5)		52		
$\theta_{JC}$	Thermal Resistance	SOT353	(Note 5)		143		°C/W
	Junction-to-Case	DFN1410	(Note 5)		190		1
			· · · · · · · · · · · · · · · · · · ·	1	l	1	

Note: 5. Test condition for SOT25, SOT353, and DFN1410: Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.



# **Switching Characteristics**

Over recommended free-air temperature range, CL = 15pF (see Figure 1)

Parameter	From	то		Vcc = 1.5 V ± 0.1V							Vcc = 5 V ± 0.5V		Unit
	(Input)	(OUTPUT)	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
t <sub>pd</sub>	A or B	Υ	1.5	7.2	1.0	5	0.5	3.5	0.6	2.9	0.7	2.9	ns

Over recommended free-air temperature range, CL = 30 or 50pF as noted (see Figure 2)

Parameter	From	то		Vcc = 1.5 V ± 0.1V							Vcc = 5 V ± 0.5V		Unit
	(Input)	(OUTPUT)	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
t <sub>pd</sub>	A or B	Y	2.4	8	1.6	5.6	0.8	4.4	0.8	3.6	0.9	3.6	ns

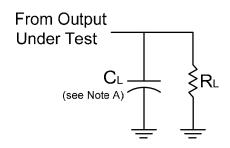
# **Operating Characteristics**

 $T_A = 25 \, {}^{\circ}C$ 

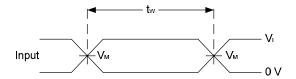
Р	arameter	Test Conditions	Vcc = 1.5 V TYP	Vcc = 1.8 V TYP	Vcc = 2.5 V TYP	Vcc = 3.3 V TYP	Vcc = 5 V	Unit
$C_{\sf pd}$	Power dissipation capacitance	f = 10 MHz	21	21	24	26	31	pF



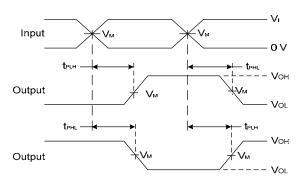
#### **Parameter Measurement Information**



Vcc	In	outs	V	0	Б	
VCC	Vı	t <sub>r</sub> /t <sub>f</sub>	V <sub>M</sub>	CL	RL	
1.5V±0.1V	V <sub>CC</sub>	≤2ns	V <sub>CC</sub> /2	15pF	1ΜΩ	
1.8V±0.15V	V <sub>CC</sub>	≤2ns	V <sub>CC</sub> /2	15pF	1ΜΩ	
2.5V±0.2V	V <sub>CC</sub>	≤2ns	V <sub>CC</sub> /2	15pF	1ΜΩ	
3.3V±0.3V	3V	≤2.5ns	1.5V	15pF	1ΜΩ	
5V±0.5V	V <sub>CC</sub>	≤2.5ns	V <sub>CC</sub> /2	15pF	1ΜΩ	



Voltage Waveform Pulse Duration



Voltage Waveform
Propagation Delay Times
Inverting and Non Inverting Outputs

Notes: A. Includes test lead and test apparatus capacitance.

B. All pulses are supplied at pulse repetition rate ≤ 10 MHz.

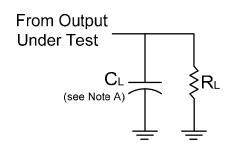
C. Inputs are measured separately one transition per measurement.

D.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{PD.}$ 

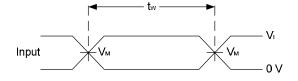
Figure 1. Load Circuit and Voltage Waveforms



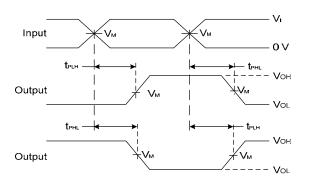
## **Parameter Measurement Information (Continued)**



Vcc	Inp	outs	V <sub>M</sub>	CL	RL	
	Vı	t <sub>r</sub> /t <sub>f</sub>	· IVI	OL.		
1.5V±0.1V	V <sub>CC</sub>	≤2ns	V <sub>CC</sub> /2	30pF	1ΚΩ	
1.8V±0.15V	V <sub>CC</sub>	≤2ns	V <sub>CC</sub> /2	30pF	1ΚΩ	
2.5V±0.2V	V <sub>CC</sub>	≤2ns	V <sub>CC</sub> /2	30pF	500Ω	
3.3V±0.3V	3V	≤2.5ns	1.5V	50pF	500Ω	
5V±0.5V	V <sub>CC</sub>	≤2.5ns	V <sub>CC</sub> /2	50pF	500Ω	



Voltage Waveform Pulse Duration



Voltage Waveform
Propagation Delay Times
Inverting and Non Inverting Outputs

Notes: A. Includes test lead and test apparatus capacitance.

B. All pulses are supplied at pulse repetition rate ≤ 10 MHz.

C. Inputs are measured separately one transition per measurement.

D.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{PD.}$ 

Figure 2. Load Circuit and Voltage Waveforms



# **Ordering Information**

 74LVCE1G 08 XXX - 7

 Logic Device
 Function
 Package
 Packing

 74 : Logic Prefix
 08 : 2-Input
 W5 : SOT25
 7 : Tape & Reel

 VCE : 1.4 to 5.5V
 AND-Gate
 SE : SOT353

FZ4: DFN1410

LVCE: 1.4 to 5.5V Family

1G : One gate

	Device	Package Packaging		7" Tape and Reel			
	Device	Code	(Note 5)	Quantity	Part Number Suffix		
Pb,	74LVCE1G08W5-7	W6	SOT25	3000/Tape & Reel	-7		
<b>B</b>	74LVCE1G08SE-7	SE	SOT353	3000/Tape & Reel	-7		
<b>Pb</b> ,	74LVCE1G08FZ4-7	FZ4	DFN1410	5000/Tape & Reel	-7		

Note: 6. Pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.



# **Marking Information**

### (1) SOT25 and SOT353

### (Top View)

5 4

XX Y W X

2

3

1

XX : Identification code

Y: Year 0~9

<u>W</u>: Week: A~Z: 1~26 week;

 $a^z$ : 27 $^5$ 2 week; z represents

52 and 53 week

 $\underline{X}$ : A $^{\sim}Z$ : Internal code

Part Number	Package	Identification Code		
74LVCE1G08W5	SOT25	PV		
74LVCE1G08SE	SOT353	PU		

### (2) DFN1410H4-6

### (Top View)

 XX: Identification Code

 $\underline{Y}$ : Year : 0~9

 $\overline{\underline{W}}$ : Week: A~Z: 1~26 week;

a~z: 27~52 week; z represents 52 and 53 week

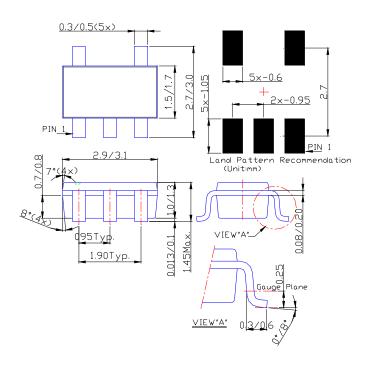
 $\underline{X}$ : A~Z: Internal code

Part Number	Package	Identification Code
74LVCE1G08FZ4	DFN1410	PV

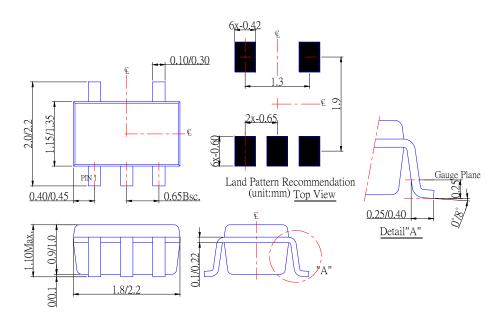


## Package Outline Dimensions (All Dimensions in mm)

### (1) Package Type: SOT25



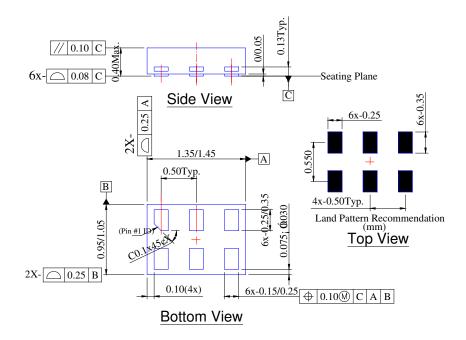
#### (2) Package Type: SOT353





# Package Outline Dimensions (All Dimensions in mm)

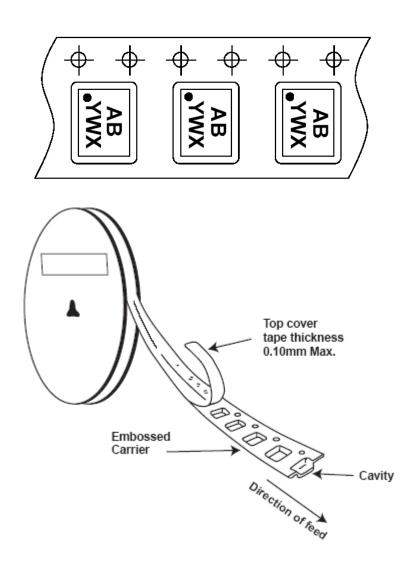
### (3) Package Type: DFN1410





# **Taping Orientation (Note 7)**

#### For DFN1410



Note: 7. The taping orientation of the other package type can be found on our website at http://www.diodes.com/datasheets/ap02007.pdf



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